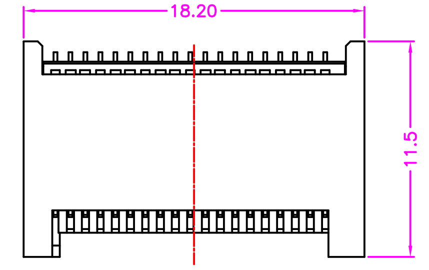
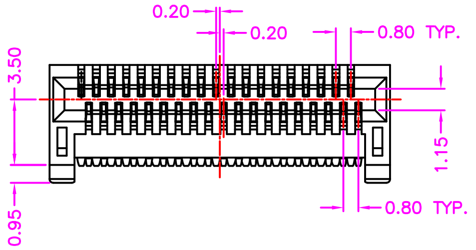
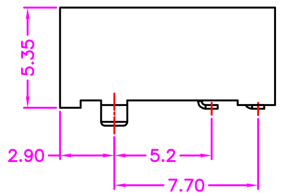
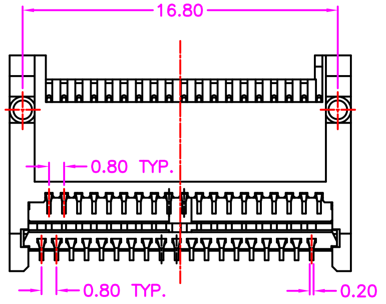








MATERIALS

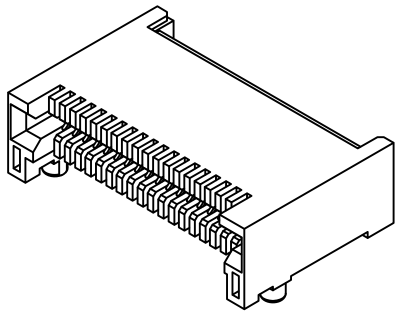
HOUSING: HI-TEMP. PLASTIC (UL 94V-0), BLACK
TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
TIN PLATING ON SOLDER TAIL

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX
DIELECTRIC WITHSTANDING: 300V AC FOR ONE MINUTE
CONTACT RESISTANCE: 80m OHMS MAX
INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V
OPERATION TEMPERATURE: −40°C~+85°C

PART NUMBER:
FQCBB – 3 8 * T – 1 * 1

SERIES
NO. OF POS.
CONTACT PLATED OPTION
1: GOLD FLASH
3: 3u" GOLD
5: 5u" GOLD
7: 15u" GOLD
9: 30u" GOLD
TIN PLATING ON SOLDER TAIL
PACKAGE OPTION
2: TAPE REEL
3: TUBE



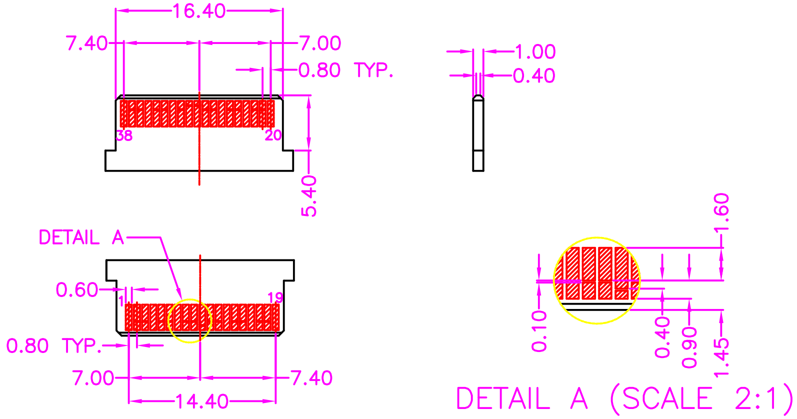
REV.	DESCRIPTION	DATE
B	MODIFY EXTERIOR	2018.8.10
A	RELEASE	2018.8.2

ZICONN
ELECTRONIC CO., LTD.
WWW.ZICONN.COM 886-3-4687695

TOLERANCES
X.±0.40 .XX±0.20
.X±0.30 .XXX±0.10

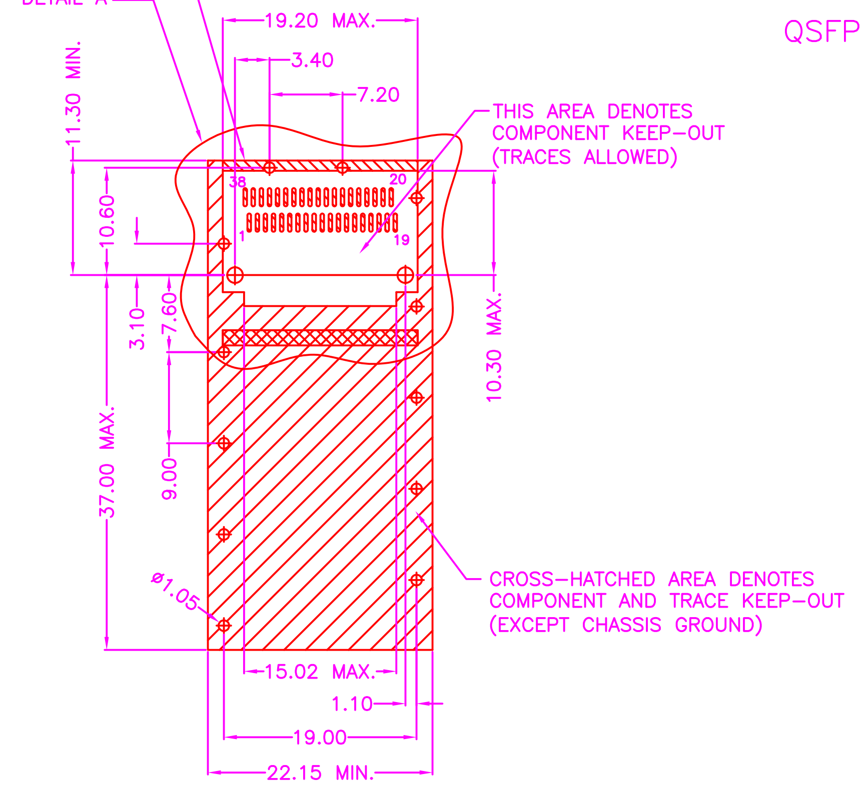
REV.	B	DRAWED BY	Zhong 2018/8/10	TITLE	QSFP CONN., 0.80mm PITCH, PCB MOUNT, SMT, WITH POST				
		APPROVED BY	Lion 2018/8/10	DRAW NO.	FQCBB-001	UNIT	MM	Sheet	1/1

C0136

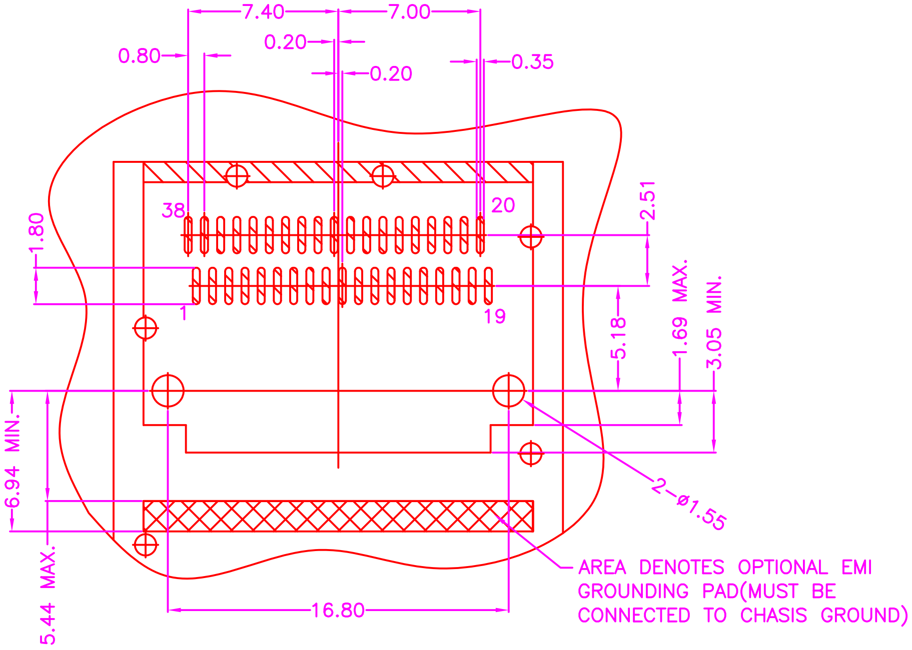


DETAIL A (SCALE 2:1)

QSFP MODULE CARD



P.C.B LAYOUT
TOP VIEW ±0.05



DETAIL A(SCALE 2:1)

ZICONN ELECTRONIC CO., LTD. WWW.ZICONN.COM 886-3-4687695	TOLERANCES X.±0.40 .XX±0.20 .X±0.30 .XXX±0.10	REV.	B	DRAWED BY	Zhong 2018/8/2	TITLE	QSFP CONN., 0.80mm PITCH, PCB MOUNT, SMT, WITH POST				
				APPROVED BY	Lion 2018/8/2	DRAW NO.	FQCBB-001	UNIT	MM	Sheet	1/1